

#### **Description**

The ICS601-01 is a low cost, low phase noise, high performance clock synthesizer for any applications that require low phase noise and low jitter. It is ICS' lowest phase noise multiplier, and also the lowest CMOS part in the industry. Using ICS' patented analog and digital Phase Locked Loop (PLL) techniques, the chip accepts a 10-27 MHz crystal or clock input, and produces output clocks up to 156 MHz at 3.3 V.

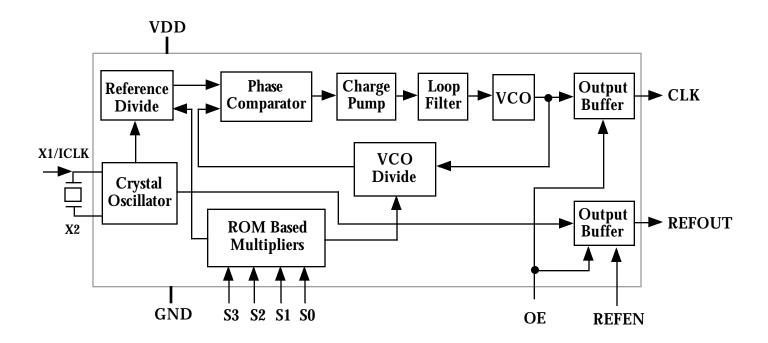
#### **Features**

• Packaged in 16 pin SOIC or TSSOP



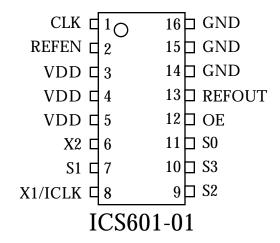
- Uses fundamental 10 27 MHz crystal, or clock
- Patented PLL with the lowest phase noise
- Output clocks up to 156 MHz at 3.3 V
- Low phase noise: -132 dBc/Hz at 10 kHz
- Output Enable function tri states outputs
- Low jitter 18 ps one sigma
- Full swing CMOS outputs with 25 mA drive capability at TTL levels
- Advanced, low power, sub-micron CMOS process
- Industrial temperature version available
- 3.3 V or 5 V operation

### **Block Diagram**





### Pin Assignment



#### **Multiplier Select Table**

S3	S2	S1	S0	CLK (see note 2 on following page)		
0	0	0	0	TEST		
0	0	0	1	TEST		
0	0	1	0	Input x1		
0	0	1	1	Input x3		
0	1	0	0	Input x4		
0	1	0	1	Input x5		
0	1	1	0	Input x6		
0	1	1	1	Input x8		
1	0	0	0	TEST		
1	0	0	1	Crystal osc. pass through (no PLL		
1	0	1	0	Input x2		
1	0	1	1	TEST		
1	1	0	0	Input x8		
1	1	0	1	Input x10		
1	1	1	0	Input x12		
1	1	1	1	Input x16		

0=connect directly to ground 1=connect directly to VDD

### **Pin Descriptions**

Number	Name	Туре	Description
1	CLK	Ο	Clock output from VCO. Output frequency equals the input frequency times multiplier.
2	REFEN	I	Reference clock enable. Turns off the buffered crystal oscillator clock (stops low) when low.
3	VDD	P	Connect to +3.3V or +5V. Must match other VDDs.
4	VDD	P	Connect to +3.3V or +5V. Must match other VDDs.
5	VDD	P	Connect to +3.3V or +5V. Must match other VDDs.
6	X2	XO	Crystal connection. Connect to a 10 - 27 MHz fundamental parallel mode crystal.
7	S1	I	Multiplier select pin 1. Determines CLK output per table above. Internal pull-up.
8	X1/ICLK	XI	Crystal connection. Connect to a 10-27 MHz fundamental parallel mode crystal, or clock
9	S2	I	Multiplier select pin 2. Determines CLK output per table above. Internal pull-up.
10	S3	I	Multiplier select pin 3. Determines CLK output per table above. Internal pull-up.
11	S0	I	Multiplier select pin 0. Determines CLK output per table above. Internal pull-up.
12	OE	I	Output Enable. Tri-states both output clocks when low. Internal pull-up.
13	REFOUT	Ο	Buffered crystal oscillator clock output. Controlled by REFEN.
14	GND	P	Connect to ground.
15	GND	P	Connect to ground.
16	GND	P	Connect to ground.

Key: I = Input with internal pull-up resistor; O = output; P = power supply connection; XI, XO = crystal connections.

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#### **Achieving Low Phase Noise**

Figure 1 shows a typical phase noise measurement in a 125 MHz system. There are a few simple steps that can be taken to achieve these levels of phase noise from the ICS601-01. Variations in VDD will increase the phase noise, so it is important to have a stable, low noise supply voltage at the device. Use decoupling capacitors of 0.1  $\mu$ F in parallel with 0.01  $\mu$ F. It is important to have these capacitors as close as possible to the ICS601-01 supply pins.

Disabling the REFOUT clock is also important for achieving low phase noise; lab tests have shown that this can reduce the phase noise by as much as 10 dBc/Hz.

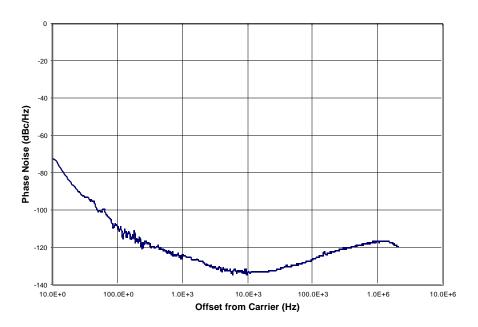


Figure 1. Phase Noise of ICS601-01 at 125 MHz out, 25 MHz crystal input. VDD = 3.3 V, REFOUT disabled.

### **External Components/Crystal Selection**

The ICS601-01 requires a minimum number of external components for proper operation. Decoupling capacitors of 0.01  $\mu F$  and 0.1  $\mu F$  should be connected between VDD and GND, as close to the part as possible. A series termination resistor of 33 may be used for each clock output. The crystal must be connected as close to the chip as possible. The crystal should be fundamental mode, parallel resonant. Do not use third overtone. For exact tuning when using a crystal, capacitors should be connected from pins X1 to ground and X2 to ground. In general, the value of these capacitors is given by the following equation, where  $C_L$  is the crystal load capacitance: Crystal caps (pF) = ( $C_L$ -5) x 2. So for a crystal with 16 pF load capacitance, two 22 pF caps can be used. For any given board layout, ICS can measure the board capacitance and recommend the exact capacitance value to use.



### **Electrical Specifications**

Parameter	Conditions	Minimum	Typical	Maximum	Units		
ABSOLUTE MAXIMUM RATINGS (note 1)							
Supply voltage, VDD	Referenced to GND			7	V		
Inputs and Clock Outputs	Referenced to GND	-0.5		VDD+0.5	V		
Ambient Operating Temperature		0		70	°C		
Ambient Operating Temperature, I version	Industrial temperature	-40		85	°C		
Soldering Temperature	Max of 10 seconds			260	°C		
Storage temperature		-65		150	°C		
DC CHARACTERISTICS (VDD = 3.3	V unless noted)						
Operating Voltage, VDD		3.0		5.5	V		
Input High Voltage, VIH, X1/ICLK pin only	Note 3	(VDD/2)+1			V		
Input Low Voltage, VIL, X1/ICLK pin only	Note 3			(VDD/2)-1	V		
Input High Voltage, VIH		2			V		
Input Low Voltage, VIL				0.8	V		
Output High Voltage, VOH, CMOS level	IOH=-4mA	VDD-0.4			V		
Output High Voltage, VOH	IOH=-12mA	2.4			V		
Output Low Voltage, VOL	IOL=12mA			0.4	V		
Operating Supply Current, IDD	No Load, 125 MHz		22	30	mA		
Short Circuit Current	Each output	±40	±60		mA		
Input Capacitance	OE, select pins		5		pF		
AC CHARACTERISTICS (VDD = 3.3	V unless noted)						
Input Frequency		10		27	MHz		
Output Frequency	at 3.3V or 5V			156	MHz		
Output Clock Rise Time	0.8 to 2.0V, no load			1.5	ns		
Output Clock Fall Time	0.8 to 2.0V, no load			1.5	ns		
Output Clock Duty Cycle	At VDD/2	45	50	55	%		
Maximum Absolute Jitter, short term, 125 MHz	No load, REF off		±50	±75	ps		
Maximum Jitter, one sigma, 125 MHz (x5)	No load, REF off		18	25	ps		
Phase Noise, relative to carrier, 125 MHz (x5)	100 Hz offset	-105	-108		dBc/Hz		
Phase Noise, relative to carrier, 125 MHz (x5)	1 kHz offset	-120	-123		dBc/Hz		
Phase Noise, relative to carrier, 125 MHz (x5)	10 kHz offset	-128	-132		dBc/Hz		
Phase Noise, relative to carrier, 125 MHz (x5)	100 kHz offset	-121	-125		dBc/Hz		

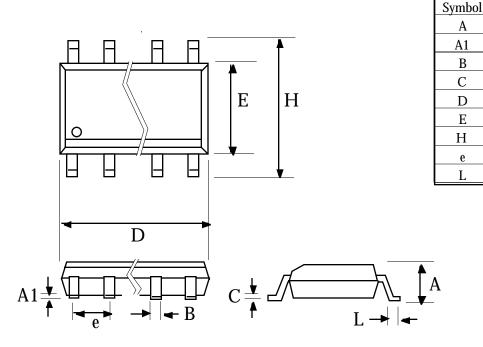
Notes:

- 1. Stresses beyond those listed under Absolute Maximum Ratings could cause permanent damage to the device. Prolonged exposure to levels above the operating limits but below the Absolute Maximums may affect device reliability.
- 2. The phase relationship between input and output can change at power up. For a fixed phase relationship, see the ICS570 or ICS670.
- 3. Switching occurs nominally at VDD/2.



### **Package Outline and Package Dimensions**

(For current dimensional specifications, see JEDEC no. 95.)



#### 16 pin narrow SOIC, TSSOP (in mm)

Max

1.75

0.25

0.51

0.25

10.00

4.00

6.20

1.27

**TSSOP** 

Max

1.20

0.15

0.30

0.20

5.10

4.50

0.75

Min

0.05

0.19

0.09

4.90

4.30

0.45

6.40 BSC

0.65 BSC

SOIC

Min

1.35

0.10

0.33

0.19

9.80

3.80

5.80

0.40

1.27 BSC

**A1** 

В

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Part/Order Number	Marking	Shipping packaging	Package	Temperature
ICS601M-01	ICS601M-01	tubes	16 pin narrow SOIC	0 to 70 °C
ICS601M-01T	ICS601M-01	tape and reel	16 pin narrow SOIC	0 to 70 °C
ICS601M-01I	ICS601M-01I	tubes	16 pin narrow SOIC	-40 to 85 °C
ICS601M-01IT	ICS601M-01I	tape and reel	16 pin narrow SOIC	-40 to 85 °C
ICS601G-01	ICS601G-01	tubes	16 pin TSSOP	0 to 70 °C
ICS601G-01T	ICS601G-01	tape and reel	16 pin TSSOP	0 to 70 °C

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